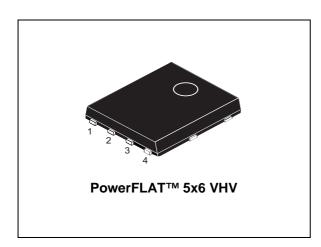
# STL7N80K5

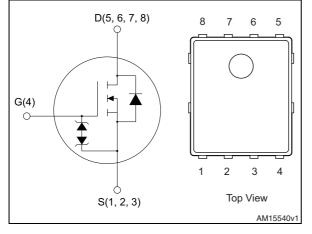
Datasheet – production data



## N-channel 800 V, 0.95 Ω typ., 3.6 A Zener-protected SuperMESH<sup>™</sup> 5 Power MOSFET in a PowerFLAT<sup>™</sup> 5x6 VHV package



#### Figure 1. Internal schematic diagram



### Features

Order code	$V_{DS}$	R <sub>DS(on)max</sub> .	I <sub>D</sub>
STL7N80K5	800 V	1.2 Ω	3.6 A

- Outstanding R<sub>DS(on)</sub>\*area
- Worldwide best FOM (figure of merit)
- Ultra low gate charge
- 100% avalanche tested
- Zener protected

### Applications

• Switching applications

### Description

This N-channel Zener-protected Power MOSFET is designed using ST's revolutionary avalancherugged very high voltage SuperMESH<sup>™</sup> 5 technology, based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance, and ultra-low gate charge for applications which require superior power density and high efficiency.

#### Table 1. Device summary

Order code	Marking	Package	Packaging
STL7N80K5	7N80K5	PowerFLAT™ 5x6 VHV	Tape and reel

DocID025551 Rev 1

This is information on a product in full production.

# Contents

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#### 1

# Electrical ratings

Symbol	Parameter	Value	Unit
V <sub>GS</sub>	Gate-source voltage	± 30	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25 \text{ °C}$	3.6	A
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>C</sub> = 100 °C	2.3	A
I <sub>DM</sub> <sup>(1),(2)</sup>	Drain current (pulsed)	14	A
P <sub>TOT</sub> <sup>(1)</sup>	Total dissipation at $T_C = 25 \ ^{\circ}C$	42	W
I <sub>AR</sub> <sup>(3)</sup>	Avalanche current, repetitive or not- repetitive (pulse width limited by T <sub>j</sub> max)	2	A
E <sub>AS</sub> <sup>(4)</sup>	Single pulse avalanche energy (starting $T_j = 25 \text{ °C}$ , $I_D = I_{AR}$ , $V_{DD} = 50 \text{ V}$ )	88	mJ
dv/dt <sup>(5)</sup>	Peak diode recovery voltage slope	4.5	V/ns
dv/dt <sup>(6)</sup>	MOSFET dv/dt ruggedness	50	V/ns
T <sub>stg</sub>	Storage temperature	- 55 to 150	°C
Тj	Max. operating junction temperature	- 33 10 130	°C

#### Table 2. Absolute maximum ratings

1. The value is rated according to  ${\sf R}_{thj\text{-}case}$  and limited by package.

2. Pulse width limited by safe operating area.

3. Pulse width limited by  $T_{jmax}$ 

4. Starting T<sub>j</sub>=25 °C,  $I_D=I_{AR}$ ,  $V_{DD}=50$  V

5. I\_{SD}  $\leq$  3.6 A, di/dt  $\leq$  100 A/µs, V\_{DS(peak)}  $\leq$  V\_{(BR)DSS}

6.  $V_{DS} \leq 640 \text{ V}$ 

#### Table 3. Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	3	°C/W
R <sub>thj-amb</sub> <sup>(1)</sup>	Thermal resistance junction-amb max	59	°C/W

1. When mounted on 1inch<sup>2</sup> FR-4 board, 2 oz Cu.



## 2 Electrical characteristics

( $T_C = 25$  °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage (V <sub>GS</sub> = 0)	I <sub>D</sub> = 1 mA	800			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = 800 V V <sub>DS</sub> = 800 V, T <sub>C</sub> =125 °C			1 50	μA μA
I <sub>GSS</sub>	Gate-body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			± 10	μA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100 \ \mu A$	3	4	5	V
R <sub>DS(on)</sub>	Static drain-source on- resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A		0.95	1.2	Ω

Table 4. On /off states

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance		-	360	-	pF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 100 V, f = 1 MHz,	-	30	-	pF
C <sub>rss</sub>	Reverse transfer capacitance	$V_{GS} = 0$	-	1	-	pF
C <sub>o(tr)</sub> <sup>(1)</sup>	Equivalent capacitance time related		-	47	-	pF
C <sub>o(er)</sub> <sup>(2)</sup>	Equivalent capacitance energy related	$V_{DS} = 0$ to 640 V, $V_{GS} = 0$	-	20	-	pF
R <sub>G</sub>	Intrinsic gate resistance	f = 1 MHz, I <sub>D</sub> =0	-	6	-	Ω
Qg	Total gate charge	V <sub>DD</sub> = 640 V, I <sub>D</sub> = 6 A,	-	13.4	-	nC
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 10 V	-	3.7	-	nC
Q <sub>gd</sub>	Gate-drain charge	(see Figure 16)	-	7.5	-	nC

1.  $C_{oss eq.}$  time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ 

2.  $C_{oss eq.}$  energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ 



	Table	e o. Switching times				
Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 3 A,	-	11.3	-	ns
t <sub>r</sub>	Rise time	$R_{G} = 4.7 \text{ W}, V_{GS} = 10 \text{ V}$	-	8.3	-	ns
t <sub>d(off)</sub>	Turn-off delay time	(see <i>Figure 15</i> ),	-	23.7	-	ns
t <sub>f</sub>	Fall time	(see <i>Figure 20</i> )	-	20.2	-	ns

Table 6. Switching times

 Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current		-		3.6	Α
I <sub>SDM</sub>	Source-drain current (pulsed)		-		14	А
$V_{SD}^{(1)}$	Forward on voltage	I <sub>SD</sub> = 6 A, V <sub>GS</sub> = 0	-		1.5	V
t <sub>rr</sub>	Reverse recovery time		-	315		ns
Q <sub>rr</sub>	Reverse recovery charge	I <sub>SD</sub> = 6 A, di/dt = 100 A/μs V <sub>DD</sub> = 60 V (see <i>Figure</i> 17)	-	2.8		μC
I <sub>RRM</sub>	Reverse recovery current		-	17.5		А
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 6 A, di/dt = 100 A/µs	-	480		ns
Q <sub>rr</sub>	Reverse recovery charge	V <sub>DD</sub> = 60 V, T <sub>j</sub> = 150 °C	-	3.8		μC
I <sub>RRM</sub>	Reverse recovery current	(see Figure 17)	-	16		А

1. Pulsed: pulse duration =  $300 \ \mu$ s, duty cycle 1.5%

Table 8. Gate-source Zener diod
---------------------------------

	Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
ĺ	V <sub>(BR)GSO</sub>	Gate-source breakdown voltage	$I_{GS}$ = ± 1mA, $I_{D}$ =0	30	-	-	V

The built-in back-to-back Zener diodes have been specifically designed to enhance not only the device's ESD capability, but also to make them capable of safely absorbing any voltage transients that may occasionally be applied from gate to source. In this respect, the Zener voltage is appropriate to achieve efficient and cost-effective protection of device integrity. The integrated Zener diodes thus eliminate the need for external components.



ZthPowerFlat\_5x6\_27

### 2.1 Electrical characteristics (curves)

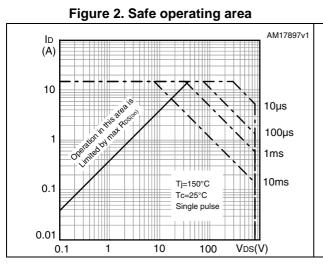
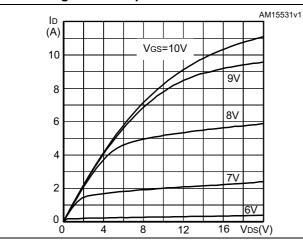
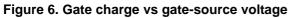


Figure 4. Output characteristics





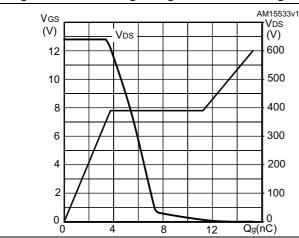


Figure 5. Transfer characteristics

10<sup>-2</sup>

10<sup>-1</sup>

Figure 3. Thermal impedance

0.1

 $Z_{th} = k R_{thJ-pcb}$  $\delta = t_p / \tau$ 

†<sub>c</sub>

10<sup>0</sup>

101 tp(s)

0.05

0.02

0.01

Single pulse

10<sup>-3</sup>

10<sup>-4</sup>

κ

10

10<sup>-2</sup>

10<sup>-3</sup>

10<sup>-5</sup>

δ=0.5

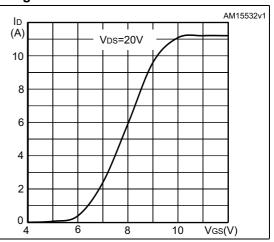
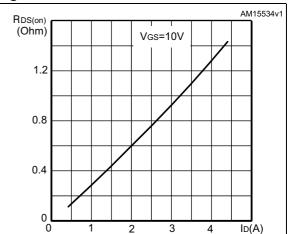


Figure 7. Static drain-source on-resistance





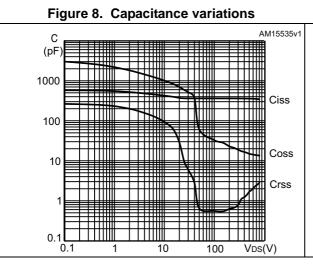


Figure 10. Normalized gate threshold voltage vs. temperature

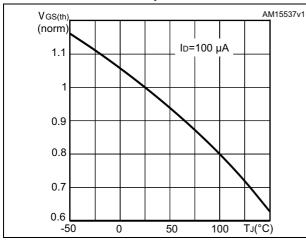
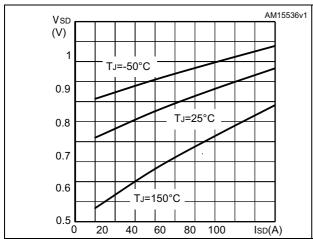


Figure 12. Drain-source diode forward characteristics





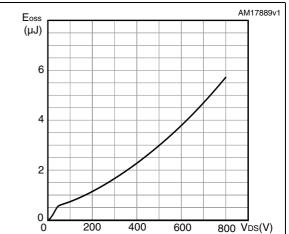


Figure 11. Normalized on-resistance vs. temperature

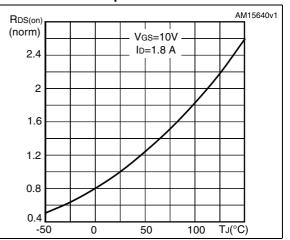
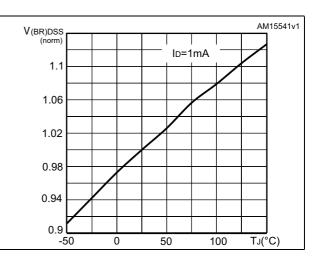


Figure 13. Normalized V<sub>DS</sub> vs. temperature





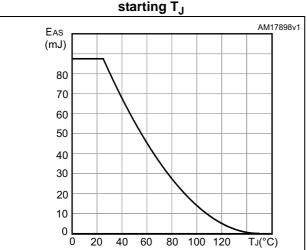


Figure 14. Maximum avalanche energy vs. starting  ${\rm T}_{\rm J}$ 

STL7N80K5



## 3 Test circuits

Figure 15. Switching times test circuit for resistive load

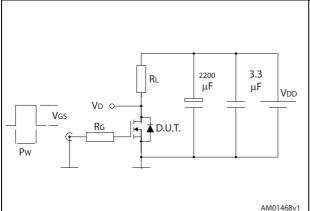


Figure 17. Test circuit for inductive load switching and diode recovery times

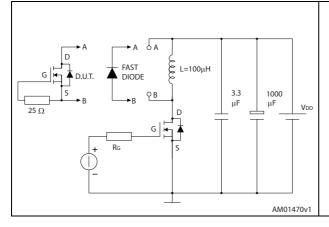


Figure 19. Unclamped inductive waveform

VD

IDM

lр

V(BR)DSS

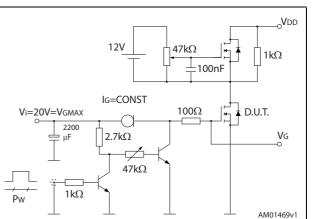
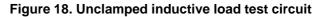
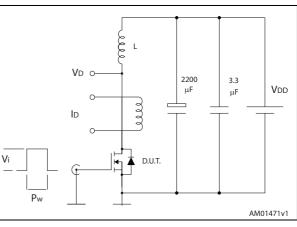
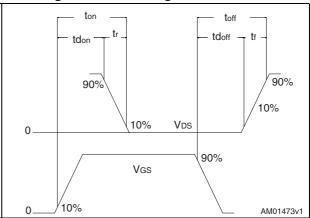


Figure 16. Gate charge test circuit







ed inductive waveform Figure 20. Switching time waveform

Vdd

AM01472v1



Vdd

# 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.



47/

DIM		mm.				
Diw	min.	typ.	max.			
A	0.80		1.00			
A1	0.02		0.05			
A2		0.25				
b	0.30		0.50			
D	5.00	5.20	5.40			
E	5.95	6.15	6.35			
D2	4.30	4.40	4.50			
E2	2.40	2.50	2.60			
е		1.27				
L	0.50	0.55	0.60			
К	2.60	2.70	2.80			
aaa		0.15				
bbb		0.15				
CCC		0.10				
eee		0.10				

Table 9. PowerFLAT<sup>™</sup> 5x6 VHV mechanical data



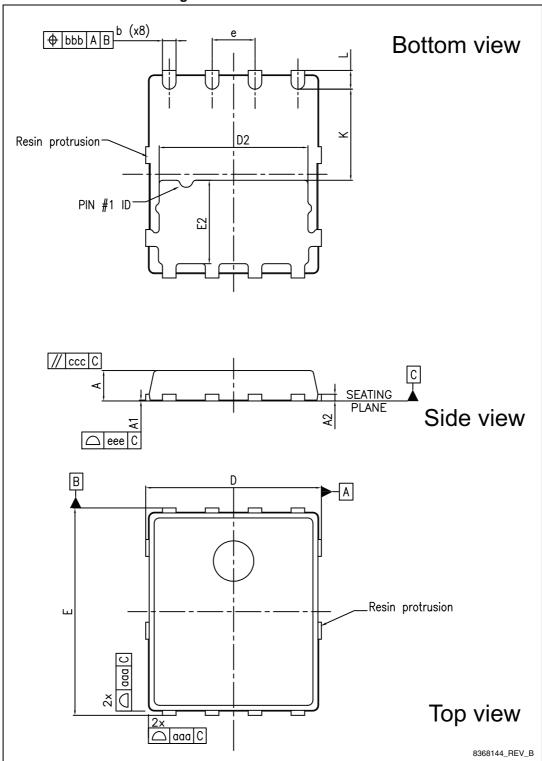


Figure 21. PowerFLAT<sup>™</sup> 5x6 VHV



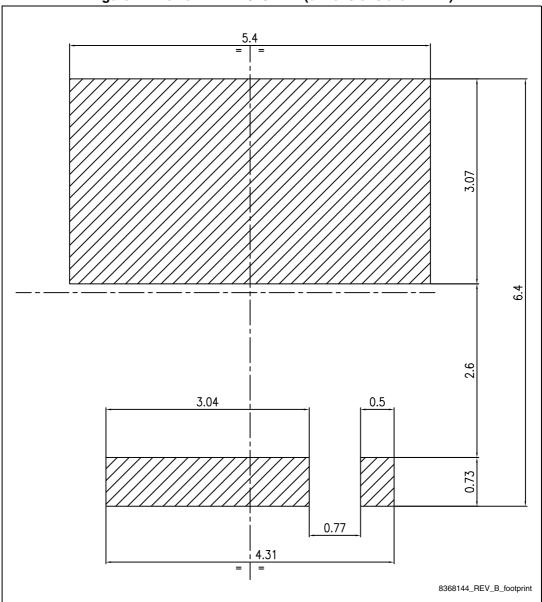
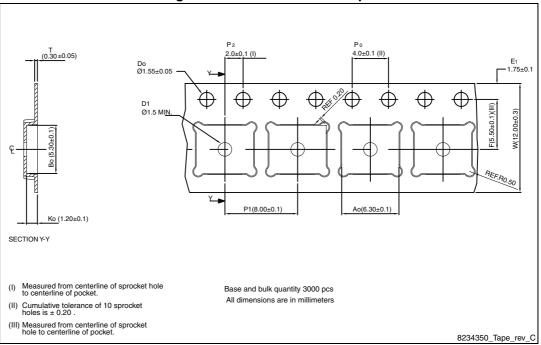


Figure 22. PowerFLAT<sup>™</sup> 5x6 VHV (dimensions are in mm)

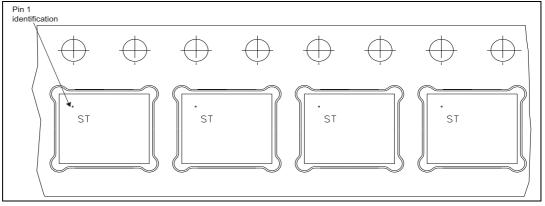


## 5 Packaging mechanical data

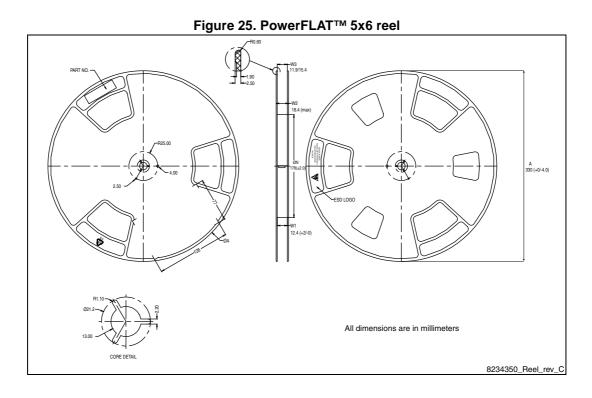














# 6 Revision history

Date	Revision	Changes
19-Nov-2013	1	First release.



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